



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



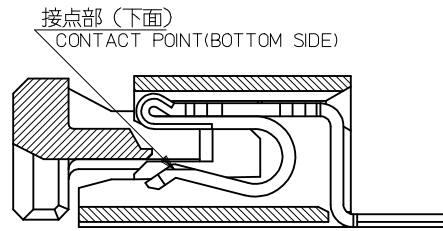
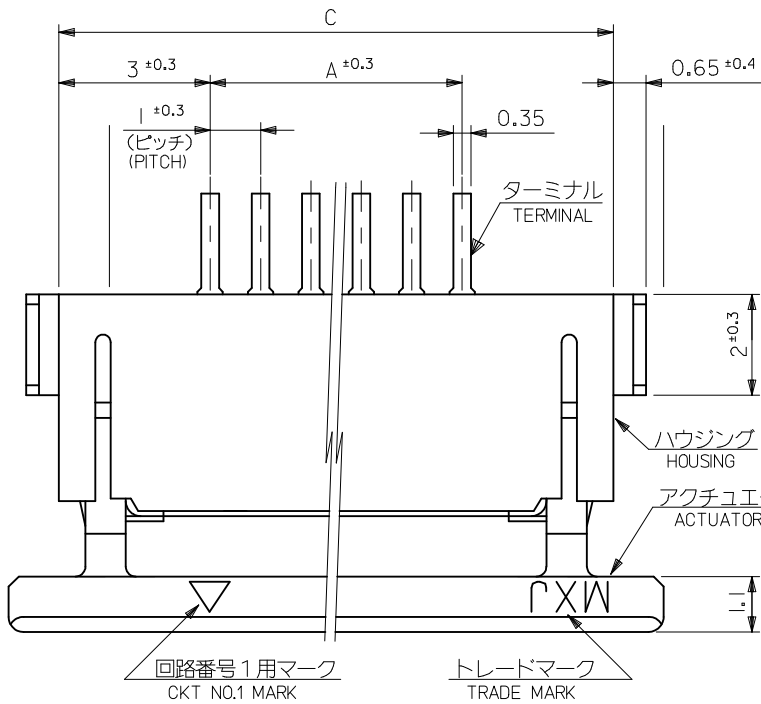
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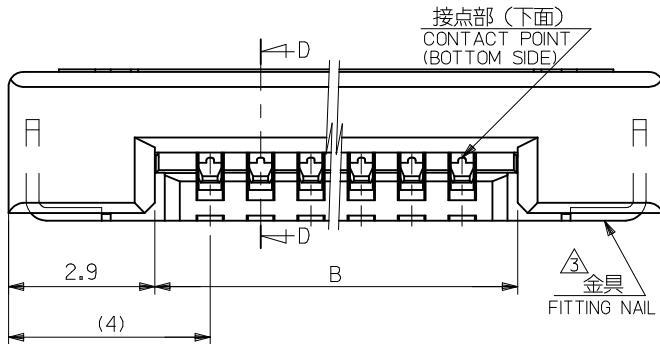
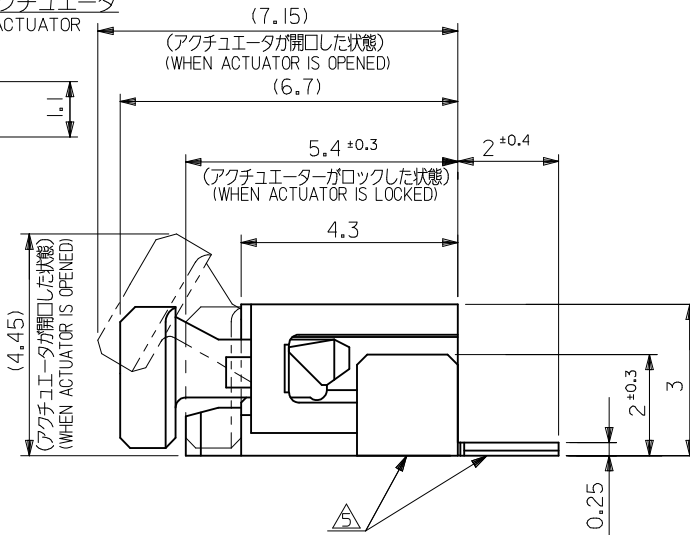
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



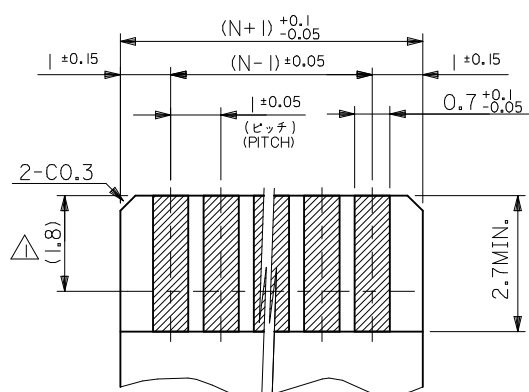


SECT. D-D

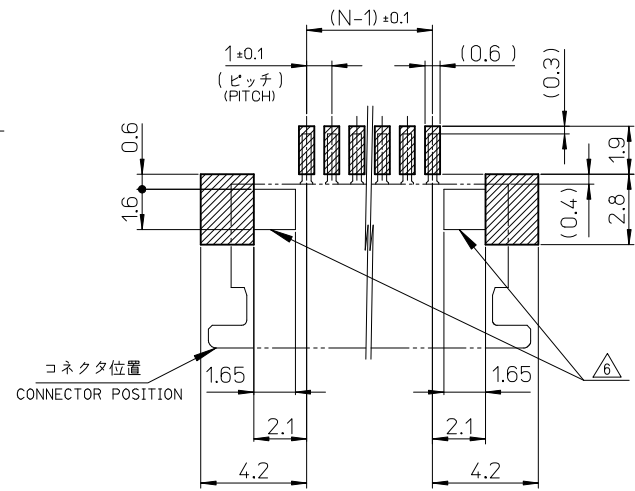


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31	27.2	25	52271-2669	26
30	26.2	24	52271-2569	25
29	25.2	23	52271-2469	24
28	24.2	22	52271-2369	23
27	23.2	21	52271-2269	22
26	22.2	20	52271-2169	21
25	21.2	19	52271-2069	20
24	20.2	18	52271-1969	19
23	19.2	17	52271-1869	18
22	18.2	16	52271-1769	17
21	17.2	15	52271-1669	16
20	16.2	14	52271-1569	15
19	15.2	13	52271-1469	14
18	14.2	12	52271-1369	13
17	13.2	11	52271-1269	12
16	12.2	10	52271-1169	11
15	11.2	9	52271-1069	10
14	10.2	8	52271-0969	9
13	9.2	7	52271-0869	8
12	8.2	6	52271-0769	7
11	7.2	5	52271-0669	6
10	6.2	4	52271-0569	5
9	5.2	3	52271-0469	4
C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUITS
52271-**-29				CONNECTOR SERIES NO.

REVISED EC NO: J2012-1390 DRWN:KNAGUMO 2012/05/10 CHKD:KAKAHASHI 2012/05/10 APPR:KMORIKAWA 2012/05/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>	SCALE <b>10:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY M.UMEDA DATE 2005/03/08	DATE 2005/03/08	TITLE <b>1.0 FPC CONN ZIF SMT                  (BOTTOM CONTACT)                  -LEAD FREE-</b>		
	MATERIAL NO. <b>SEE CHART</b>		CHECKED BY K.TOYODA DATE 2005/03/08	DATE 2005/03/08	DOCUMENT NO. <b>SD-52271-038</b>		
	SIZE <b>A3</b>		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SHEET NO. 1 OF 2	



(仕上り厚さ: 0.3±0.05)  
(THICKNESS: 0.3±0.05)  
適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(SCALE 10:1)



参考基板レイアウト  
RECOMMENDED PCB  
PATTERN DIMENSIONS(REF.)  
(SCALE 5:1)

注記 NOTES

- △1 接点部までの嵌合長さ。  
LENGTH TO CONTACT POINT.
- 2. 使用材料 MATERIAL
  - ハウジング : 46 NYLON, UL94V-0  
HOUSING
  - アクチュエータ : PPS, UL94V-0  
ACTUATOR
  - ターミナル : リン青銅 (t=0.25)  
TERMINAL PHOSPHOR BRONZE (t=0.25)
  - メッキ : 接点部: 金メッキ : 0.1 MICROMETER MIN.  
CONTACT PORTION : GOLD PLATING : 0.1 MICROMETER MIN.  
半田付部: 錫メッキ : 1.0 MICROMETER MIN.  
SOLDERING PORTION : TIN PLATING : 1.0 MICROMETER MIN.  
下地: ニッケルメッキ : 1.0 MICROMETER MIN.  
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
  - 金具 : 銅合金 (t=0.25)  
FITTING NAIL CAPPER ALLOY (t=0.25)
  - メッキ: 錫メッキ : 1.0 MICROMETER MIN.  
PLATING : TIN PLATING : 1.0 MICROMETER MIN.
  - 下地: ニッケルメッキ : 1.0 MICROMETER MIN.  
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.

- △3 パターンはくり止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING  
OF P.C.B. PATTERN.
- 4. エンボステープ梱包時は、アクチュエータがロックした状態とする。  
IN THE PACKAGE, ACTUATOR OF PART NO.54550-\*\*\*29 SHOULD BE LOCKED.
- △5 テール及び金具の平坦度は、0.15以下とする。  
TAIL AND NAIL COPLANRITY TO BE 0.15 MAXIMUM.
- △6 パターン書き込み禁止エリア  
NO FOOT PRINT AREA.

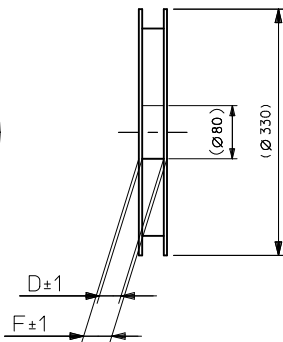
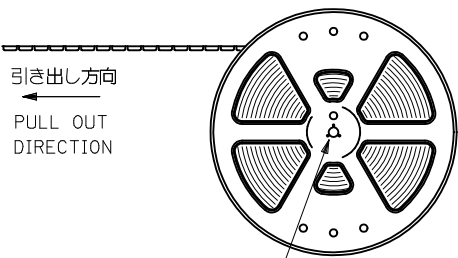
FPC について :

打抜き方向は、導体側から補強板側を推奨致します。  
補強フィルム材質は、ポリイミドを推奨致します。  
接着剤は、熱硬化接着剤を推奨致します。

ABOUT FPC :

RECOMMENDED PUNCHER DIRECTION :  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2012-1390 DRWN:KNAGUMO 2012/05/10 CHKD:KAKAHASHI 2012/05/10 APP:KMORIKAWA 2012/05/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08		
ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-52271-038	SHEET NO. 2 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

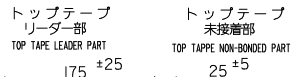


NOTES

1. 製品番号 52271-\*\*29 の梱包状態はアクチュエータがロックした状態とする。  
詳細寸法については 図面 SD-52271-038 を参照下さい。  
IN THE PACKAGE, AUTUATOR OF PART NO. 52271-\*\*29 SHOULD BE LOCKED  
RE DETAILED DIMENSIONS, SEE SD-52271-038.

2. 梱包数量：1000個/リール  
NUMBER OF CONNECTORS：1000 PCS/REEL

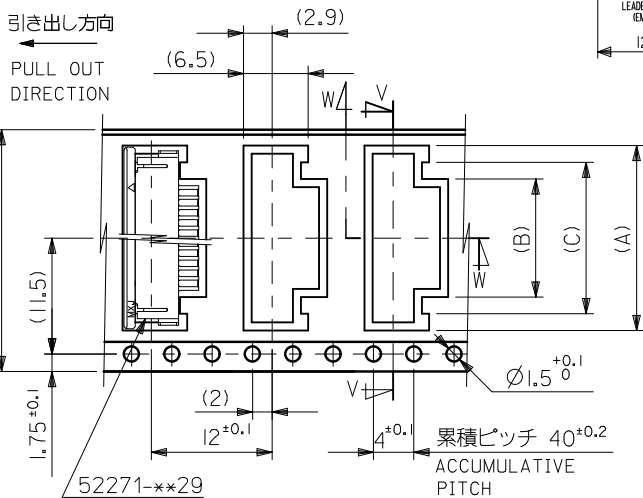
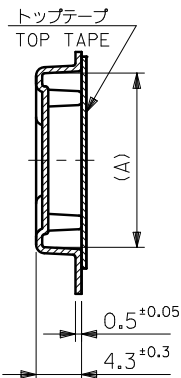
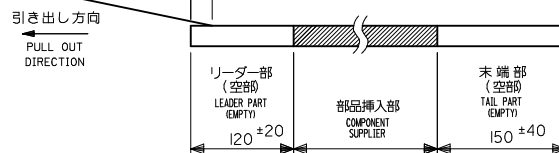
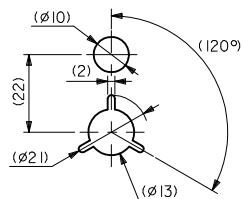
3. リードテープ長さ LEAD TAPE LENGTH



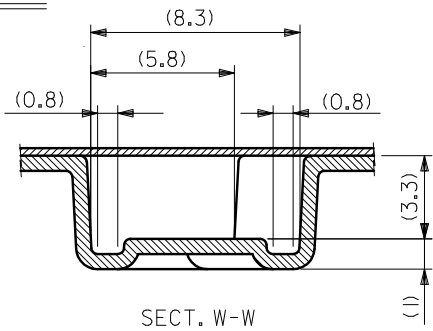
4. カバーテープの剥離強度については、IEC60286-3に準拠  
COVER TAPE PEEL FORCE IS DEFINED BY IEC60286-3

5. 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

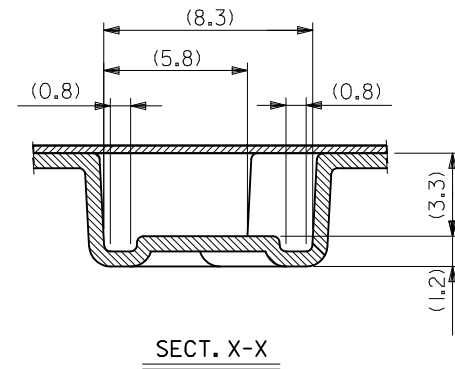
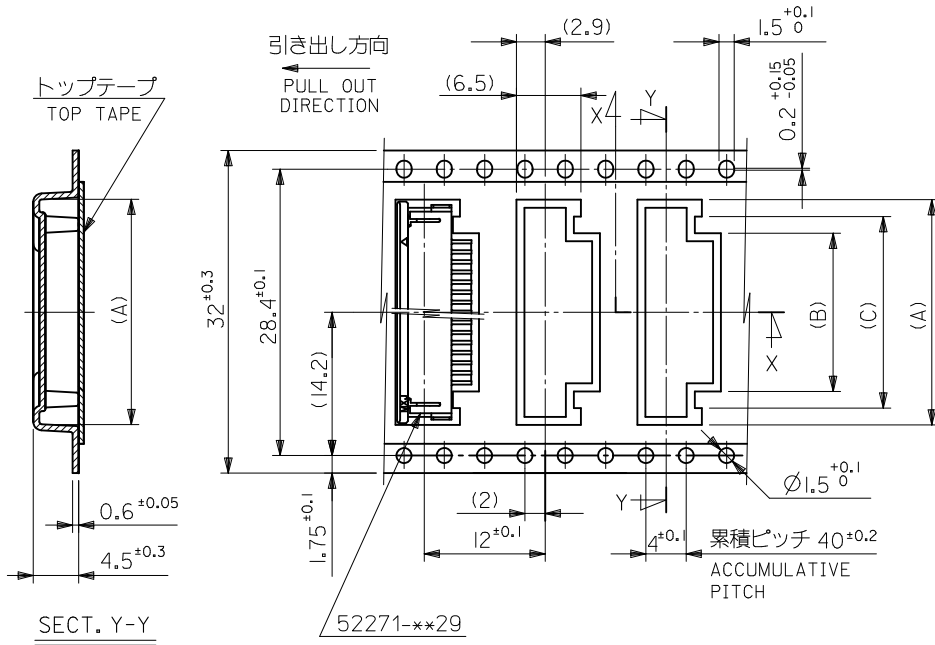
6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.



24	29.4	25.4	15	11.4	18.3	52271-1169	11
			14	10.4	17.3	52271-1069	10
			12	8.4	15.3	52271-0869	8
			11	7.4	14.3	52271-0769	7
			10	6.4	13.3	52271-0669	6
			9	5.4	12.3	52271-0569	5
			8	4.4	11.3	52271-0469	4
			キャリアテープ幅 CARRIER TAPE WIDTH			F	D

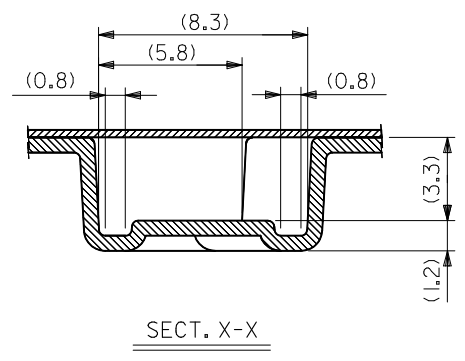
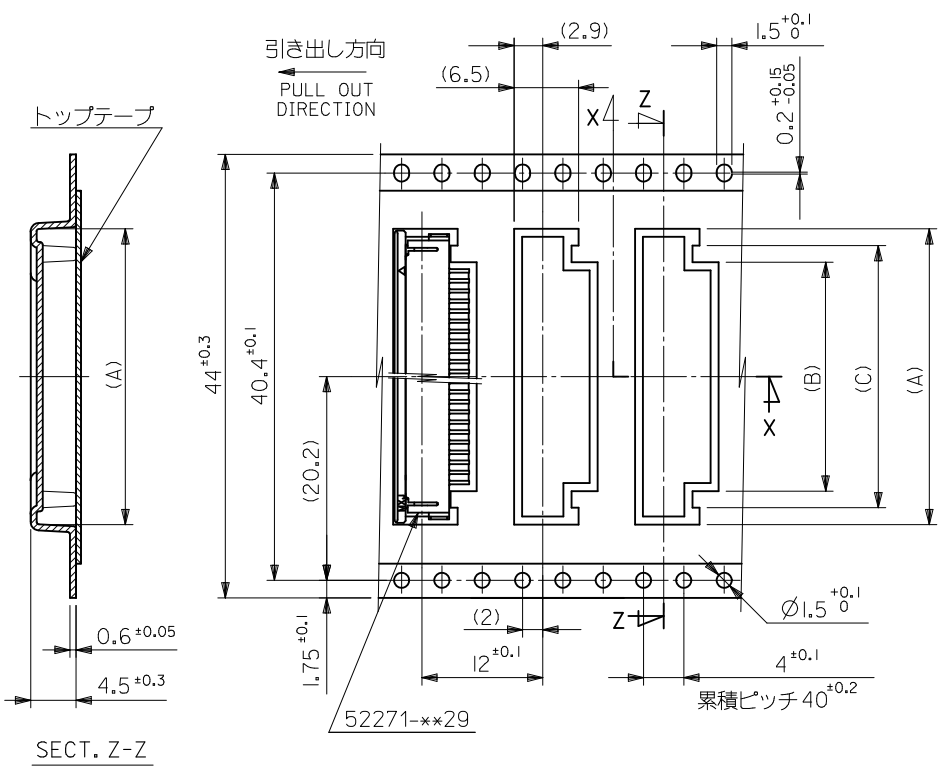


REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORI KAWA 2010/06/09	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		MODEL NO. 52271-**69		
		10 UNDER	±0.2	DRAWN BY M. UEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-						
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2005/03/08	MOLEX INCORPORATED						
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2005/03/08							
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52271-039		SHEET NO. 1 OF 4				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION												



32	37.4	33.4	20	16.4	23.35	52271-1669	16		
			19	15.4	22.35	52271-1569	15		
			18	14.4	21.35	52271-1469	14		
			17	13.4	20.35	52271-1369	13		
			16	12.4	19.35	52271-1269	12		
キャリアテープ幅 CARRIER TAPE WIDTH			F	D	(C)	(B)	(A)	MATERIAL NO.	極数 CKT.

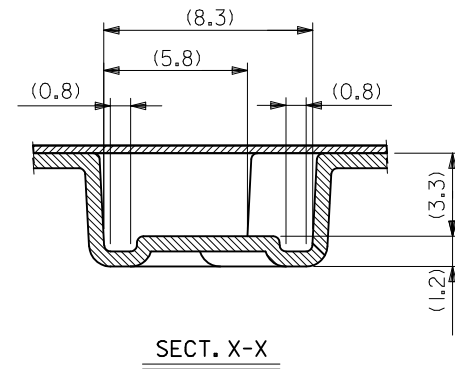
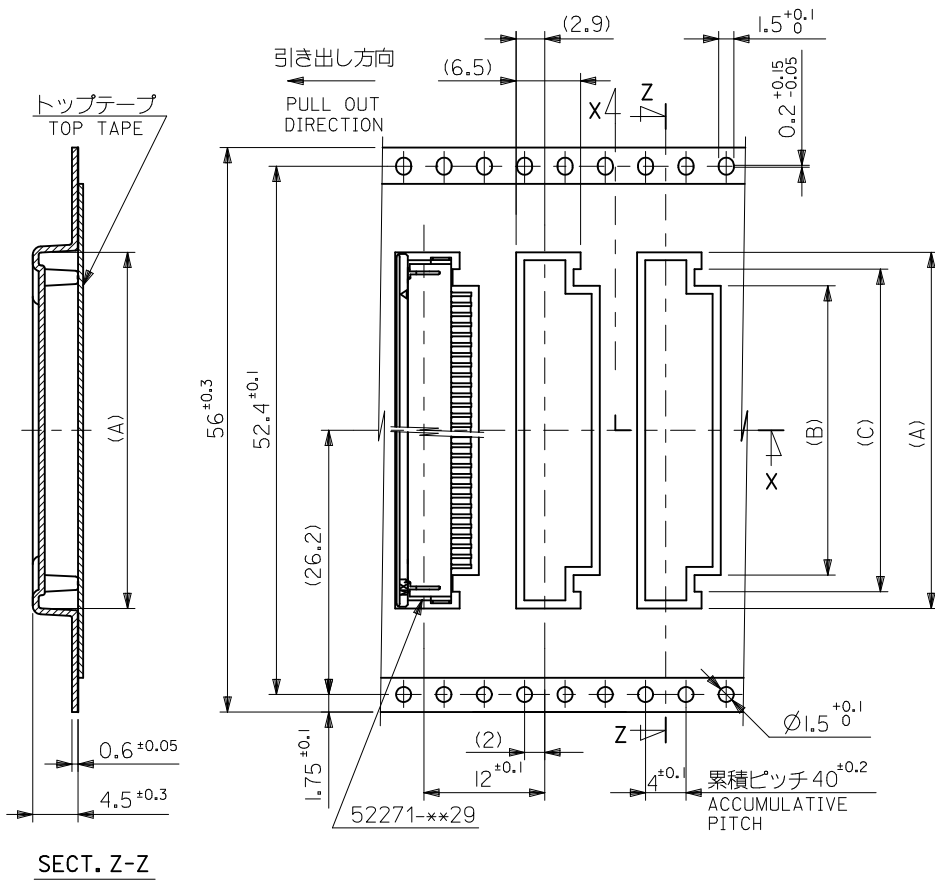
REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**-29 -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2005/03/08	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2005/03/08	DOCUMENT NO. SD-52271-039			
		ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SHEET NO. 2 OF 4			
REV	REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



44	49.4	45.4	31	27.4	34.35	52271-2769	27		
			29	25.4	32.35	52271-2569	25		
			28	24.4	31.35	52271-2469	24		
			26	22.4	29.35	52271-2269	22		
			25	21.4	28.35	52271-2169	21		
			24	20.4	27.35	52271-2069	20		
			23	19.4	26.35	52271-1969	19		
			22	18.4	25.35	52271-1869	18		
			21	17.4	24.35	52271-1769	17		
キャリアテープ幅			F	D	(C)	(B)	(A)	MATERIAL NO.	極数

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHK'D: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08	DOCUMENT NO. SD-52271-039		SHEET NO. 3 OF 4	
	ANGULAR ±3 °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								





SECT. Z-Z

SECT. X-X

56	61.4	57.4	34	30.4	37.35	52271-3069	30
			32	28.4	35.35	52271-2869	28
キャリアテープ幅 CARRIER TAPE WIDTH			F	D	(C)	(B)	(A)
						MATERIAL NO.	極数 CKT.

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHK'D: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08	MOLEX INCORPORATED DOCUMENT NO. SD-52271-039 SHEET NO. 4 OF 4			
		30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08				
		ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	